

ABSTRACT OF THE DISCLOSURE

5 An attempt is made to reduce the size of
a multichip package obtained by mounting a plurality
of surface acoustic wave elements having different
frequency characteristics in one package. For this
purpose, when a plurality of surface acoustic wave
elements are face-down bonded to a package, the
ultrasound wave application direction is set to
a direction substantially perpendicular to the
10 direction in which the surface acoustic wave elements
are juxtaposed.

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